

Title (en)

Contact pin for electronic components, especially printed-circuit boards.

Title (de)

Kontaktstift für elektronische Bauteile, insbesondere Leiterplatten.

Title (fr)

Broche de connexion pour composants électroniques, particulièrement circuits imprimés.

Publication

**EP 0152769 A2 19850828 (DE)**

Application

**EP 85100511 A 19850118**

Priority

DE 8404681 U 19840216

Abstract (en)

1. A contact pin for electronic elements, in particular printed circuit boards, which can be inserted with press fit into an opening in the printed circuit board, the press fit portion (1) of the pin lying in the printed circuit board against the rim of the opening in the printed circuit board with at least two peripheral portions (4), and the contact pin being provided in the press fit portion with a central, weblike upset zone (S) which interconnects the two opposite peripheral portions and in which plastic deformation takes place during the pressing in process, characterized in that the web (2) of the upset zone (S) has enlargements (6) at least in some areas on both sides along the length of the press fit portion (1), said enlargements being formed symmetrically to each other (axis R).

Abstract (de)

Bei einem Kontaktstift für elektronische Bauteile, insbesondere Leiterplatten, der mit einer zentralen stegartigen Stauchungszone versehen ist, sind zur Stabilisierung des Verformungsvorgangs beim Einpressen des Kontaktstifts beidseitig des Sitzabschnitts ballig geformte Verdickungen vorgesehen.

IPC 1-7

**H01R 9/09**

IPC 8 full level

**H01R 12/32** (2006.01); **H01R 12/34** (2006.01); **H01R 12/55** (2011.01); **H01R 12/58** (2011.01)

CPC (source: EP)

**H01R 12/58** (2013.01)

Cited by

DE102017214465A1; EP0132704A3; DE4002486A1; US4857019A; EP0372368A3; EP0367660A3; DE3909310A1; DE102006048337B3; DE102022133352A1; DE102022129018A1; WO2019034608A1; US11152723B2; DE102017214465B4

Designated contracting state (EPC)

AT CH DE FR IT LI NL SE

DOCDB simple family (publication)

**EP 0152769 A2 19850828**; **EP 0152769 A3 19851002**; **EP 0152769 B1 19871111**; AT E30813 T1 19871115; DE 3560973 D1 19871217; DE 8404681 U1 19850103

DOCDB simple family (application)

**EP 85100511 A 19850118**; AT 85100511 T 19850118; DE 3560973 T 19850118; DE 8404681 U 19840216